



Material Content Data Sheet



Sales Product Name		BSP742RI		Issued		3. July 2019		
MA#		MA005337964						
Package		PG-DSO-8-24		Weight*		83.23 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.539	1.85	1.85	18487	18487
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		108	
	non noble metal	zinc	7440-66-6	0.036	0.04		431	
	non noble metal	iron	7439-89-6	0.717	0.86		8617	
wire	non noble metal	copper	7440-50-8	29.121	34.99	35.90	349899	359055
	noble metal	gold	7440-57-5	0.472	0.57	0.57	5672	5672
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1184
encapsulation	plastics	epoxy resin	-	4.532	5.45		54455	
	inorganic material	silicondioxide	60676-86-0	44.632	53.62	59.19	536263	591902
leadfinish	non noble metal	tin	7440-31-5	0.814	0.98	0.98	9779	9779
plating	noble metal	silver	7440-22-4	0.650	0.78	0.78	7813	7813
glue	plastics	epoxy resin	-	0.106	0.13		1276	
	noble metal	silver	7440-22-4	0.501	0.60	0.73	6016	7292
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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